

# Index

## A

alignment, 14, 31  
assembly tooling, 32  
precision support posts, 35  
principles, 31  
alumina, 16  
aluminum nitrate, 16  
ANSYS, 18, 65  
APV25, 4, 21, 71, 91, 110  
characterization at low T, 80  
operation modes, 77  
Araldite®, 18, 39  
argon, 25, 54  
assembly tooling  
  small prototype module, 31

## B

beam  
  secondary, 87  
shape, 96  
X5, 87  
bonding, 76  
breakdown, 3, 74  
bulk  
  leakage current, 83  
modulus, 48  
temperature fluid, 22

## C

capillary pipe, 25, 54  
carbon fiber, 17, 19, 54  
charge collection efficiency, 3  
cold finger, 54  
colloidal silica, 50  
composites  
  mechanical properties, 46  
  theoretical models, 48  
  thermal dilatation, 42  
compressor, 54, 65  
convective boiling, 30  
cooling  
  cryogenic micro pump, 25  
  evaporative cooling, 25  
  micro tube, 53  
  warm compressor, 26  
covariance, 90  
cryostat, 86  
cyanoacrylate, 39  
Czochralski silicon, 71, 73

## D

deconvolution mode, 79  
depletion voltage, 75  
design  
  cryogenic module, 13  
  large prototype module, 72  
  small prototype module, 14  
detector  
  processing, 73  
dose, 3

## E

edgeless  
  insensitive layer, 105  
  silicon microstrip sensors, 81  
  silicon pad sensors, 81  
edgeless silicon detectors, 10  
effective gap, 101  
elastic modulus, 46  
elastic scattering, 81  
electrical characterization  
  results, 78  
electrical module, 71  
elongation at break, 46  
emissivity, 22  
epoxy  
  filled, 39  
  layer thickness, 51, 67  
mechanical properties, 46  
thermal conductivity, 19  
thermal dilatation, 42  
thermoelastic properties, 39  
error  
  gap width (edgeless), 101  
  thermal dilatation tests, 45  
expansion coefficient, 49

## F

feedthrough, 16  
filling factor, 48, 49  
finite element, 18, 65  
fit  
  least squares, 90  
  parameters, 98  
  results, 98  
  tracking, 88  
Float Zone silicon, 4, 71, 73  
flow  
  single-phase, 56  
  two-phase, 56

full-depletion potential, 3  
fused quartz, 39, 42, 47

## G

gap  
  effective gap, 101  
  fit parameter, 98  
metrology, 84, 103  
model function, 96  
gluing jigs, 32

## H

H3 Beam, 87  
hardener, 39  
heat  
  exchanger, 54  
  load, 21, 55  
heat transfer coefficient, 22, 27  
  convective boiling, 30, 66  
  laminar flow, 29  
  nucleate boiling, 30, 66  
  single-phase flow, 27  
  turbulent flow, 29  
  two-phase flow, 30  
homogenous flow model, 57  
hybrid, 54  
  characterization, 77

## J

jigs, 32

## L

laminar flow  
  pressure drop, 57  
leakage current, 3, 21, 74  
luminosity, 3, 1  
  measurement, 8  
  upgrade, 4

## M

material engineering, 4  
material properties, 18  
mechanical properties  
  epoxies, 46  
  filled epoxies, 47  
mesh, 21, 66  
metrology  
  gap measurement, 103  
  inlet pipe diameter, 58  
micro tube, 15, 53, 107  
MINUIT, 98, 101

mobility, 78  
model function, 96, 101  
module  
  components, materials, 15, 72  
  design principles, 13  
  geometry, 21, 72  
  simulation, 65  
  thermal simulation, 18  
  thermal tests, 59  
modulus  
  bulk, 48  
  shear, 48  
  Young, 46, 49  
Monte Carlo, 95

## N

noise, 78  
nucleate boiling, 30

## O

ORCA, 88, 99  
oxygenated silicon, 4, 6

## P

peak mode, 79  
pedestal, 79  
photolithography, 73  
pitch adapter, 14, 16, 54, 75  
plateau, 102  
Poisson's ratio, 49  
pressure drop, 27, 57  
processing, 73  
Pyrex®, 16

## Q

quality factor, 56

## R

R&G Type L, 18  
radiation dose, 3  
radiation hard epoxies, 18  
readout electronics, 4, 71, 80,  
  110  
  low temperature tests, 77  
residuals, 91  
resistivity, 75  
rise time, 79  
Rutapox, 39

## S

silica glass, 16  
silicon  
  Czochralski, 73  
  edgeless detector, 10  
  Float Zone, 73  
  large detector, 71, 73  
  material properties, 17  
silicone adhesive, 39

simulation  
  Monte Carlo, 95  
  thermal, 22  
  thermal tests, 65  
sintering, 76  
smearing, 91  
space charge region, 3  
spacer, 71  
SPS, 87  
strip, 73  
Stycast®, 18, 39  
sub-cooled liquid, 56  
support plate, 75

## T

TEC, 85  
Teflon®, 32  
telescope  
  CMS tracker, 85  
tensile strength, 18  
  filled epoxies, 46  
thermal  
  conductivity, 3, 107  
  dilatation, 3, 107  
thermal conductivity, 14, 17  
thermal dilatation, 14, 42  
thermal radiation, 22, 54, 59, 60  
thermal shield, 54  
thermal tests  
  compressor system, 54  
  experimental setup, 53  
  meta-stable states, 63  
  results, 59

thermoelastic

  properties, 18  
TOB, 85, 92, 99  
total cross section, 81  
tracker  
  CMS tracker, 85  
  LHC, 1  
  resolution, 95  
transconductance, 78  
turbulent flow  
  pressure drop, 57  
two-phase flow, 15, 25, 58, 107  
Type L, 39

## V

vacuum, 16, 54  
vapour fraction, 56

## Y

yield strength, 46  
Young modulus, 18, 39